



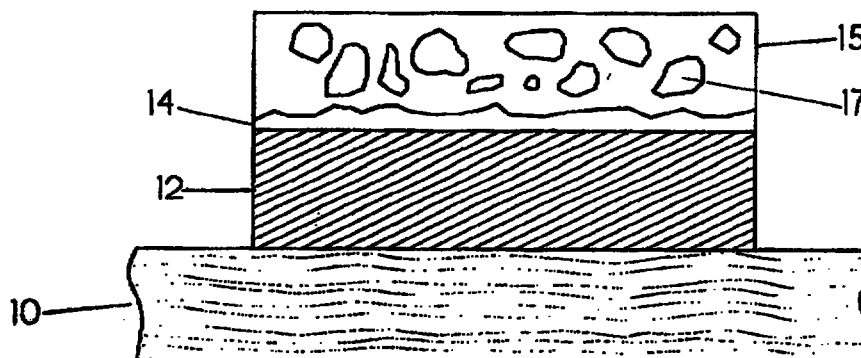
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(54) Title: ORGANIC-METALLIC COMPOSITE COATING FOR COPPER SURFACE PROTECTION



(57) Abstract

Copper-containing surfaces (12) of substrates such as laminated electronic circuit boards (10) are protected by organometallic coatings (15) comprising organic compounds selected from the group consisting of benzimidazoles, alkylimidazoles, benzotriazoles and alkyltriazoles, substituted or unsubstituted, and metal particles (17) of solder-wettable metals or metal solders. The metal particles can be thermally formed *in situ* from metallic compounds such as noble metal acetates, acetylacetonates and carbonates.